

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

Group Art Unit:

Inventors: Belov et al.

Filed:

Title: High Selectivity Colloidal
Silica Slurry

Examiner:

INFORMATION DISCLOSURE STATEMENT

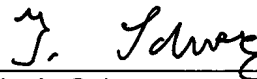
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 CFR 1.51, 1.56 and 1.97 to 1.99, the list of references cited on the attached Form PTO-1449 is made of record to assist the Patent and Trademark Office in its examination of this application. A copy of each of the references cited is enclosed herewith. Since we have not received an Office Action on the merits, no fee is believed to be due.

This disclosure statement should neither be construed as a representation that a search has been made, nor as an admission that the information cited is, or is considered to be, material to patentability as defined in 1.56(b).

Respectfully submitted,



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Date: November 19, 2003

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| Form PTO-1449 (Rev. 8-83) | U.S. Department of Commerce | Atty. Docket No. D-21,389 | Serial No. |
| Information Disclosure Citation (Use several sheets if necessary) | | Applicants Belov et al. | |
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